Testing & Diagnosis of Fine-pitch Wafers and Advanced Packages

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Advanced packaging solutions require more and more known-good-die (KGD) testing.

When Copper pads or Copper pillars are involved, this translates in a continuous request for customized and optimized probing solutions, to achieve the unprecedented performances that are needed by customers to cope with increasing electrical requirements and with the involved complexity of geometries.

This paper will summarize the results of a long lasting and relentless development, where TPEG™ MEMS probing technologies have been customized and adapted over time to support a wide range of requested solutions, from processors to leading edge mobile memory interfaces (Wide I/O).

In details, for each probing technology, C_RES stability data on Customer wafers and the relevant obtained lifetime performances will be presented.